



# PASSIVE COMPONENTS

*Keys to Enabling Advanced Future System Designs*



# OUTLINE

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## **Current State**

Where Are We At Today

## **How Did We Get Here**

Drivers

## **Examples**

Where Capacitors Enable Performance

**Where Are We Going & What Does  
The Future Hold**



# ADVANCEMENT OF CAPACITOR TECHNOLOGY

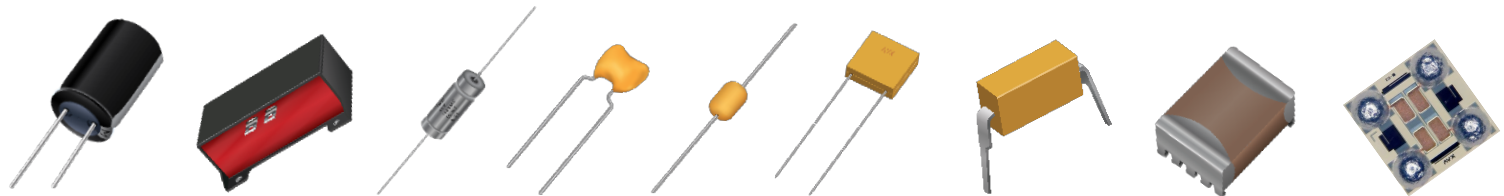
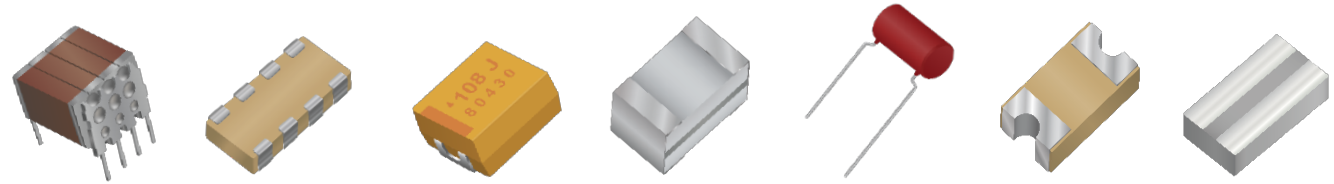
## *Then vs Now*

### *State of the Art Technology Then*



**Leyden Jar**  
Source: [ETHW.org](http://ETHW.org)

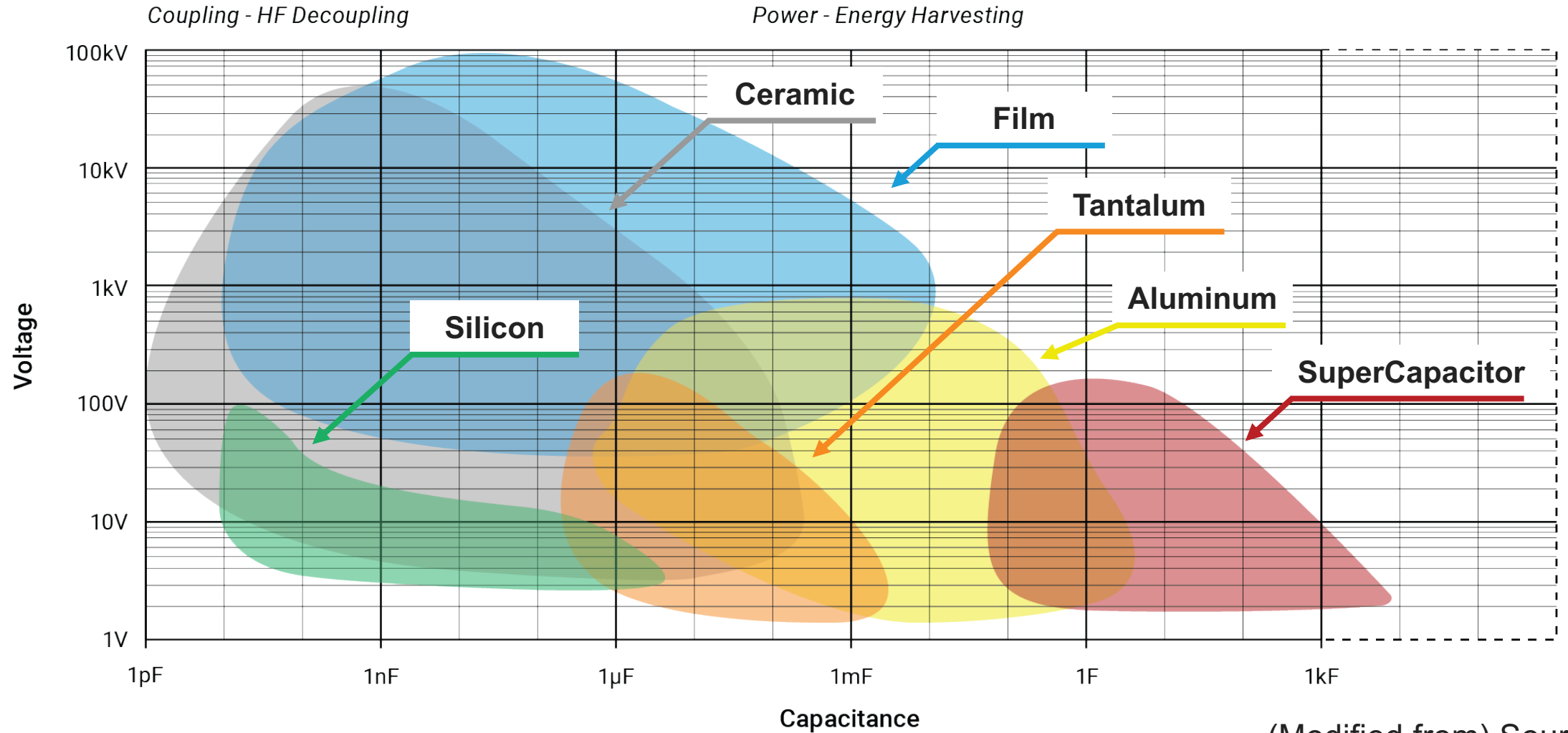
In 1746, the Leyden Jar was considered to be the very first capacitor. It was the first device capable of storing an electric charge.



*State of the Art Technology Now*

# WHERE ARE CAPACITORS TODAY

- Ceramic Capacitors
- Film Capacitors
- Silicon Capacitors
- Solid Tantalum Capacitors
- Aluminum Electrolytic Capacitors
- Super Capacitors



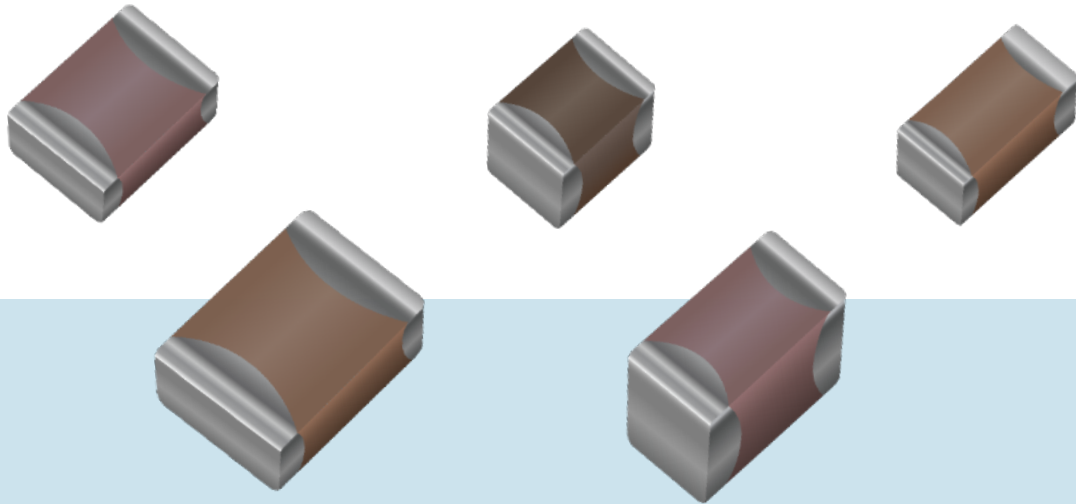
(Modified from) Source: EPCI

# 2019

## WHERE WE ARE TODAY

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*Just experienced shortages and market conditions unlike anything we have seen before*



Source:

[The Wall Street Journal](#)

BUSINESS

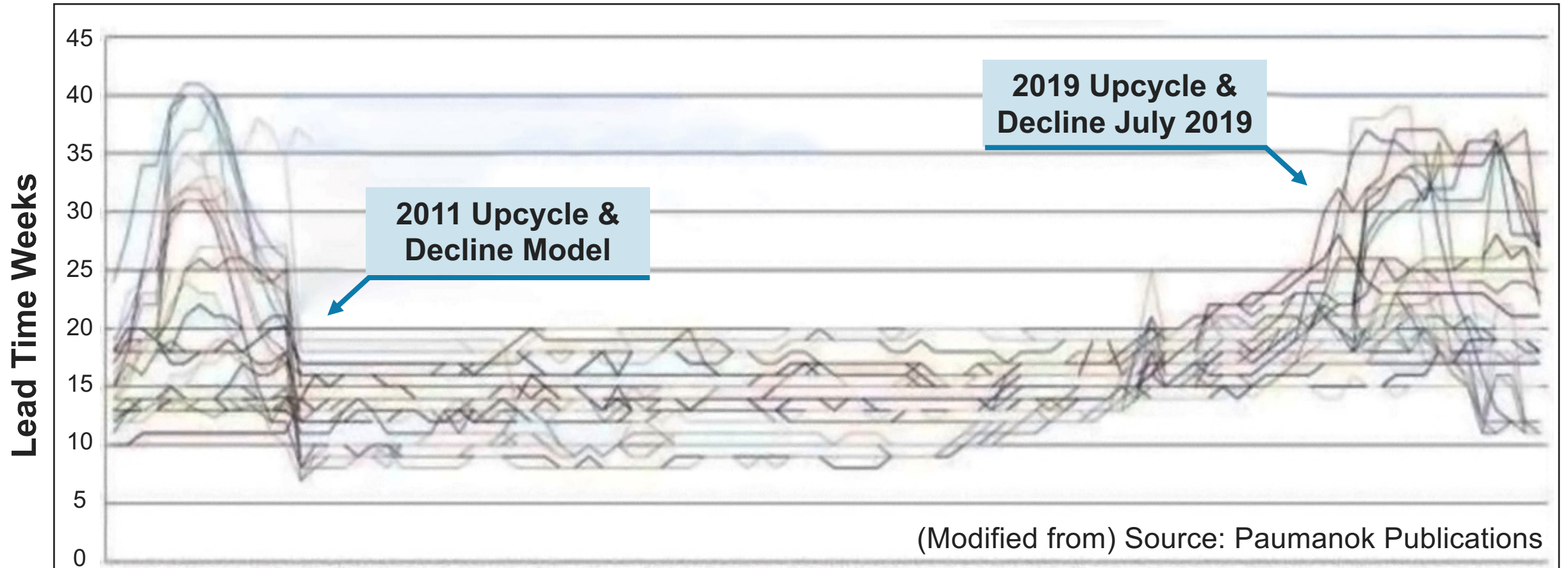
### Parts Shortages Crimp U.S. Factories

As suppliers struggle to meet demand, Caterpillar fights to fill orders and Oshkosh idles crane output



PHOTO: MIKE BLAKE/REUTERS

# CYCLIC NATURE OF CAPACITOR SHORTAGES



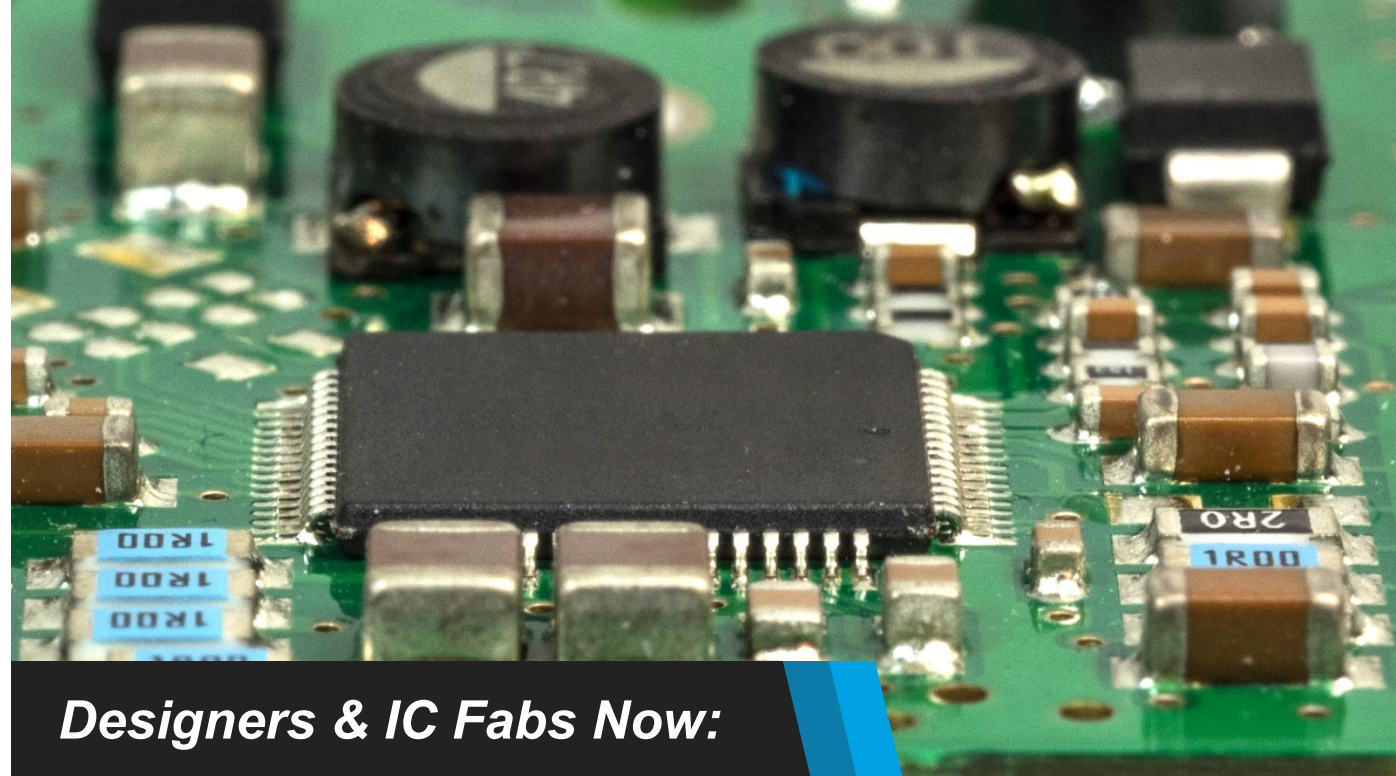
**100 month period of time**

29 Different Capacitor Types Tracked

# SUPPLY SHORTAGE IMPACTS:

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*Design Engineers were driven to align usage with parts readily available – **compromises made***



*Designers & IC Fabs Now:*

- 1 Exploring Design Changes to Reduce Component Count
- 2 Increased Collaboration in New IC Types Causing Accelerated Innovation / Rate of Change

# DRIVERS -

## MASSIVE NEW MARKETS AND APPLICATION NEED

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*The next 10 years will be nothing like anything we have seen*

### Rapid Emergence Of Whole New Markets, Systems & Applications:

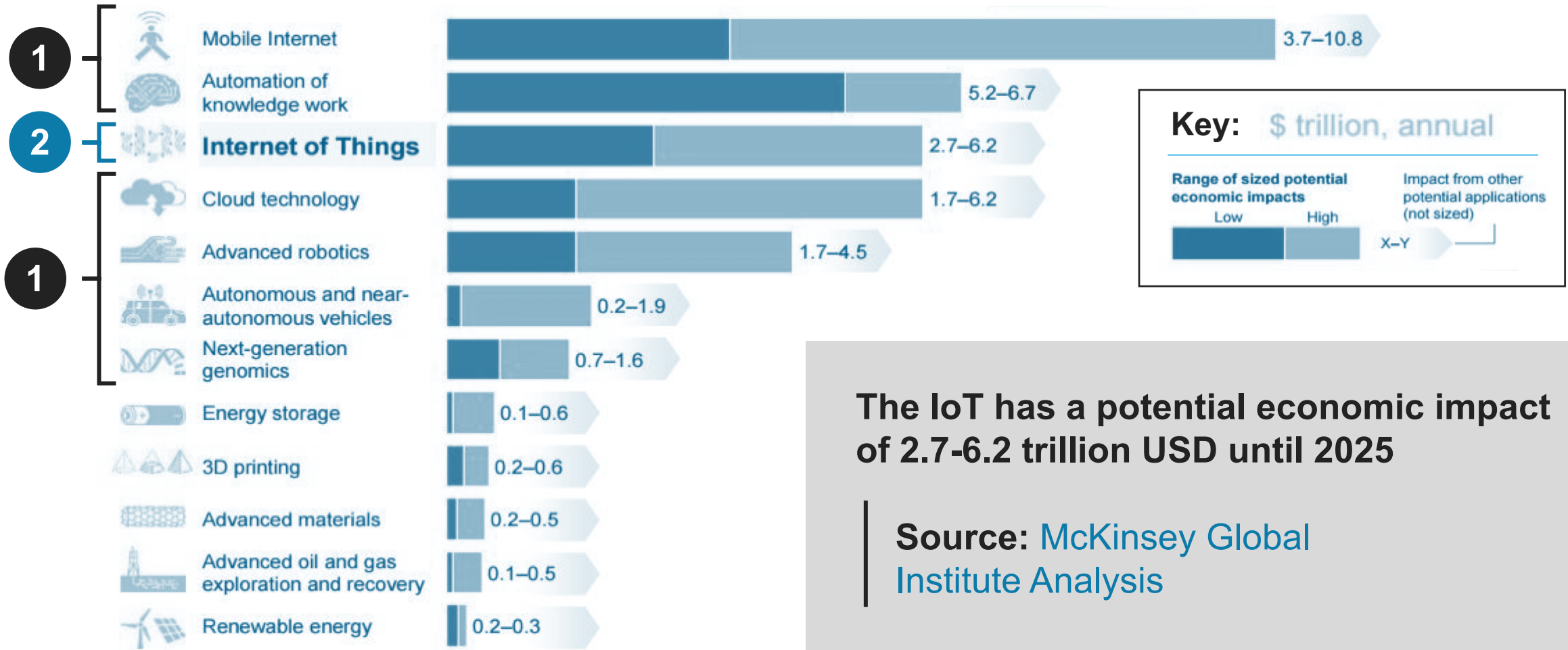
- Virtual Reality / Augmented Reality
  - EVs
  - Autonomous Vehicles
  - 5G
  - IoT Cloud
- Smartphones/ PDA
  - Charging – Wireless Low Power & Wired High Power
  - Medical Electronics
  - Advanced Robotics



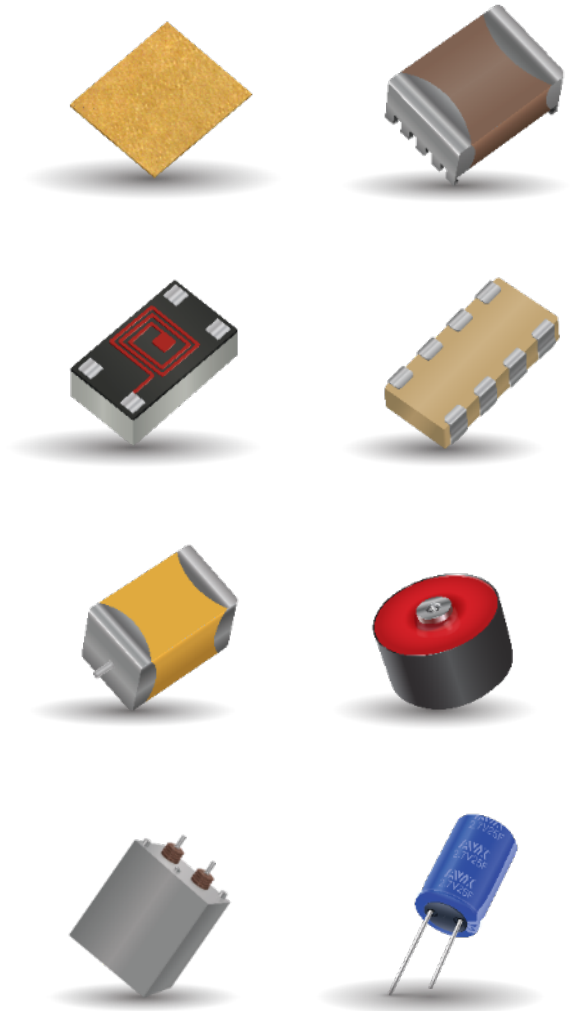
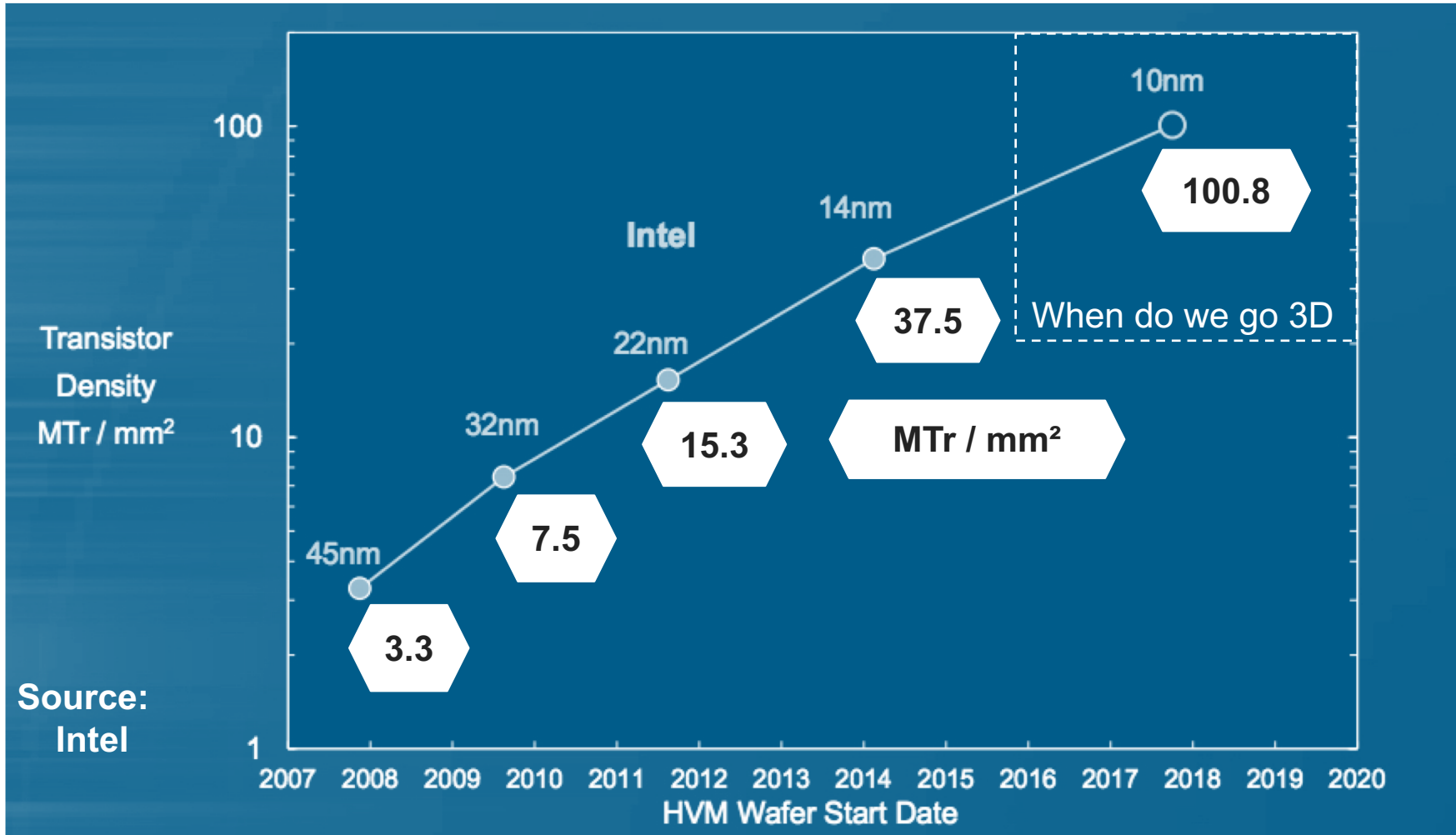


# MULTIPLE KEY GROWTH AREAS

## LETS DIVE INTO 2 'SECTORS'



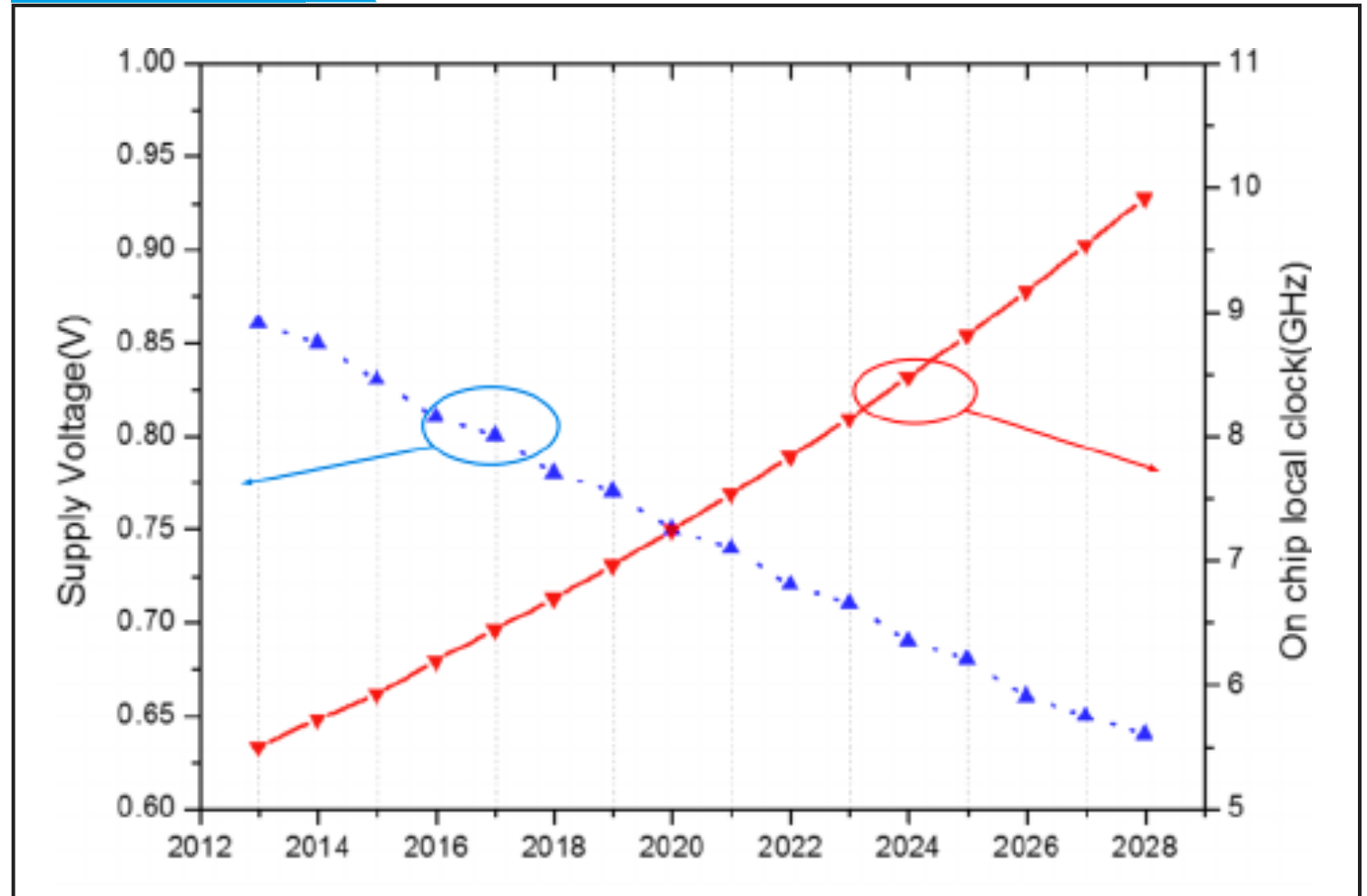
# EXAMPLE - WHERE CAPACITORS ENABLE PERFORMANCE: ADVANCED SEMICONDUCTORS



# ***DIE SCALING HAS DROPPED IC SUPPLY VOLTAGE***

- *Capacitors job decoupling more critical*
- *Clock & data speeds making Di/Dt drawn larger*

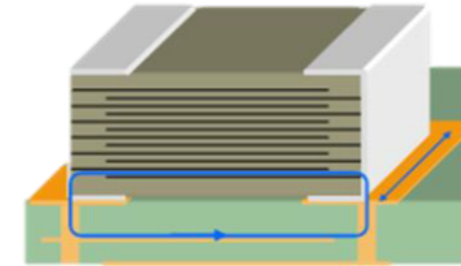
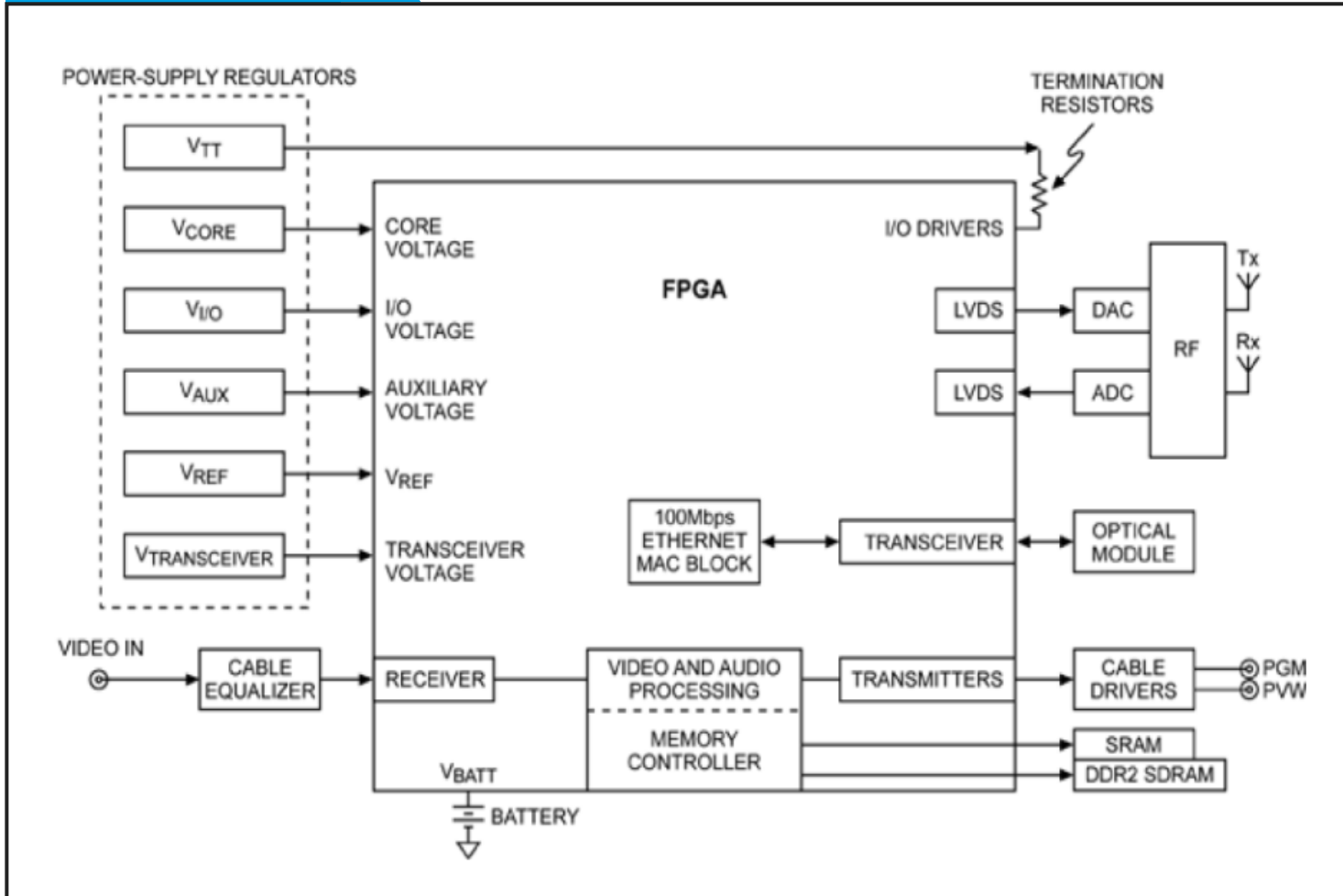
Source: ITRS



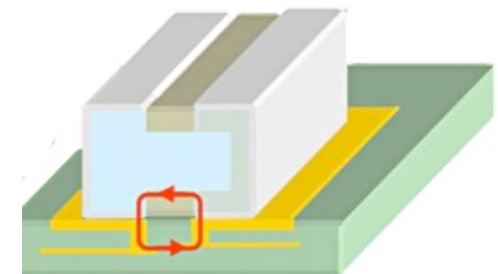
# TYPICAL FPGA 6 OR MORE DIFFERENT VOLTAGES

Source:

Maxim



0805 MLCC  
ESL ~ 600pH



0508 LGA  
ESL ~ 27pH

# TYPICAL FPGA 6 OR MORE DIFFERENT VOLTAGES

Source:

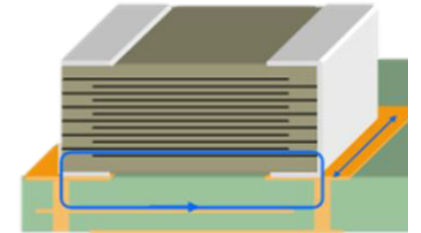
Maxim

Table 1. Xilinx Virtex-7 Power-Supply Requirements

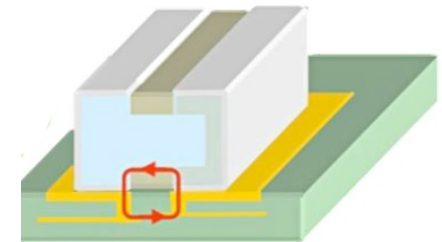
Power Rail	Nominal Voltage (V)	Tolerance	Description
VCCINT	1.0*	±3%*	Voltage supply for the internal core logic
VCCAUX	1.8	±5%	Voltage supply for auxiliary logic
VCCO	1.2 to 3.3	1.11V to 3.45V**	Voltage supply for I/O banks
MGTA VCC	1.0	±3%	Voltage supply for GTX transceiver
MGTA VTT	1.2	±30mV	Voltage supply for GTX transceiver termination circuits

\*The lowest-speed "-1L" version of the Virtex-7 has a 0.9V core voltage with a ±30mV tolerance.

\*\*The specification for 3.3V HR I/O banks is 3.45V (max). The specification for 1.8V HR I/O banks is 1.89V (max).



0805 MLCC  
ESL ~ 600pH



0508 MLCC  
ESL ~ 45pH

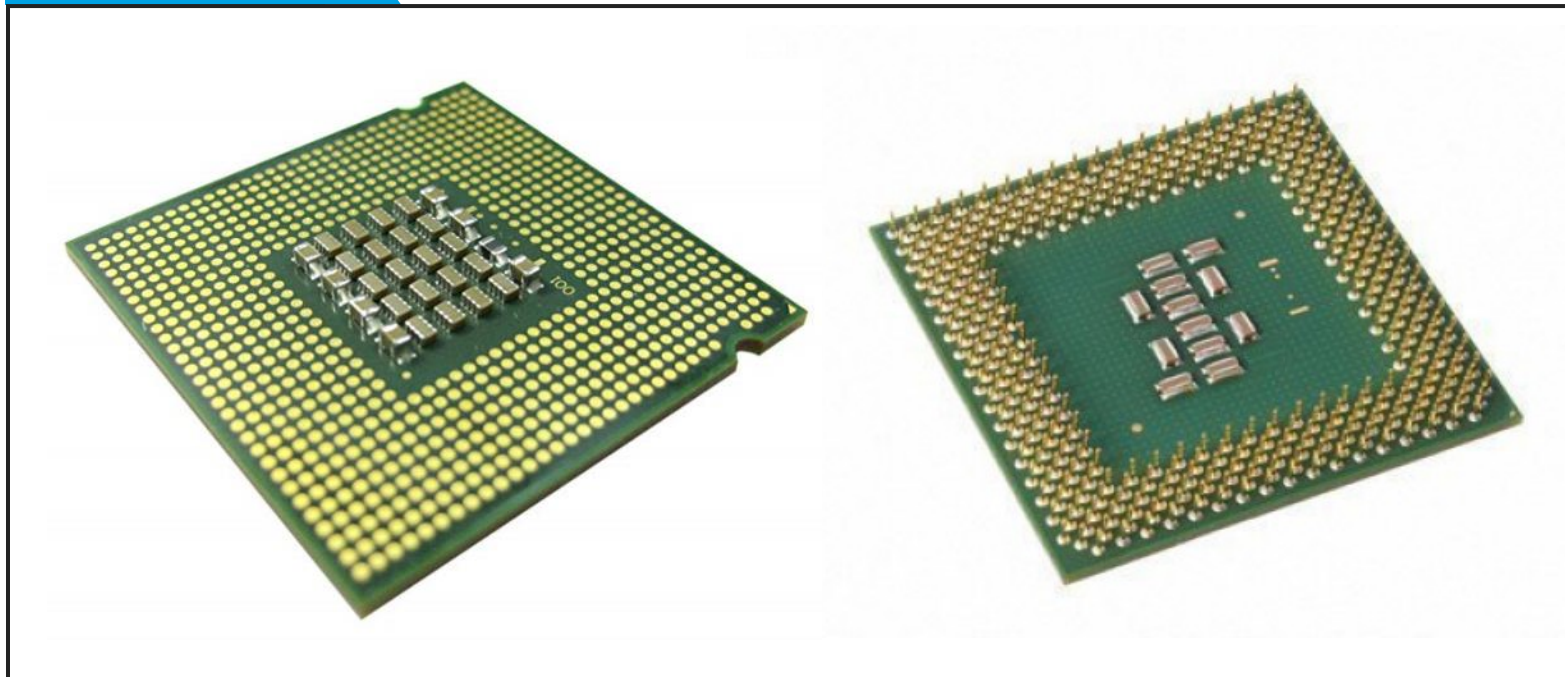
# TODAYS SOLUTION

## LOW INDUCTANCE MLCCS OR SMALL CASE MLCCS IN LOW INDUCTANCE CONFIGURATION

- 0402 Caps Inside 0.8 mm Pitch BGA
- 0201 Caps Placed 90° Rotated Allows For More Caps Underneath The BGA Area

Source:

Maxim



Source:

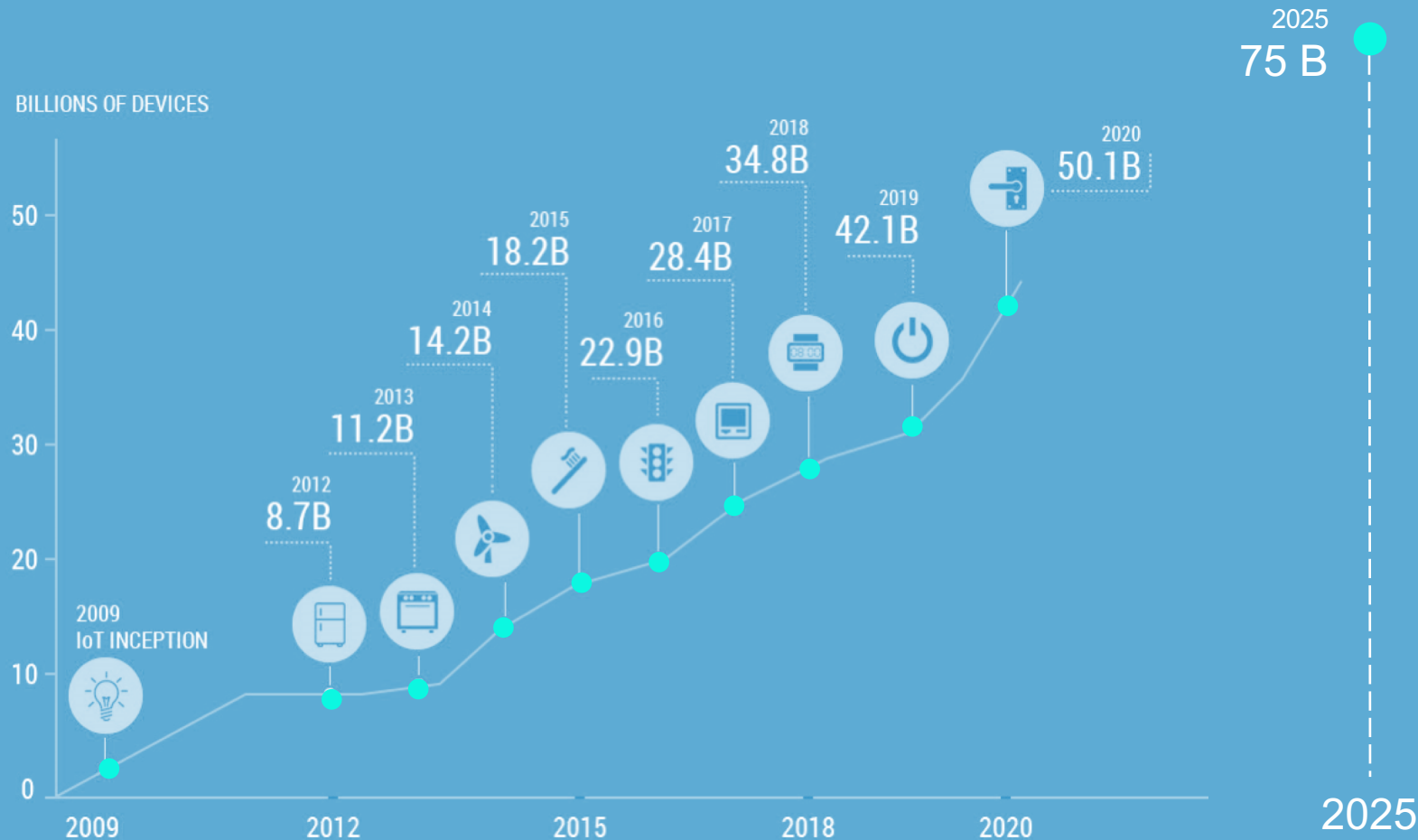
Intel



# EXAMPLE - WHERE CAPACITORS ENABLE PERFORMANCE: IoT } 2

## GROWTH OF THE IoT

**Key:** ● Per Statista 37 billion 2019, 75 Billion 2025  
● Per Ericsson 18 billion 2019



The Number of Connected Devices will Exceed 75 Billion by 2025

Source: CISCO

# IoT WILL DRIVE PASSIVE COMPONENT VOLUMES

IoT WILL DRIVE ENERGY HARVESTING METHODS, CIRCUITS & MODULES



**Hard to replace the battery here.**

An important opportunity within IoT is  
**Energy Harvesting.**



***IoT Allows:***

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24/7 remote  
monitoring of  
anything

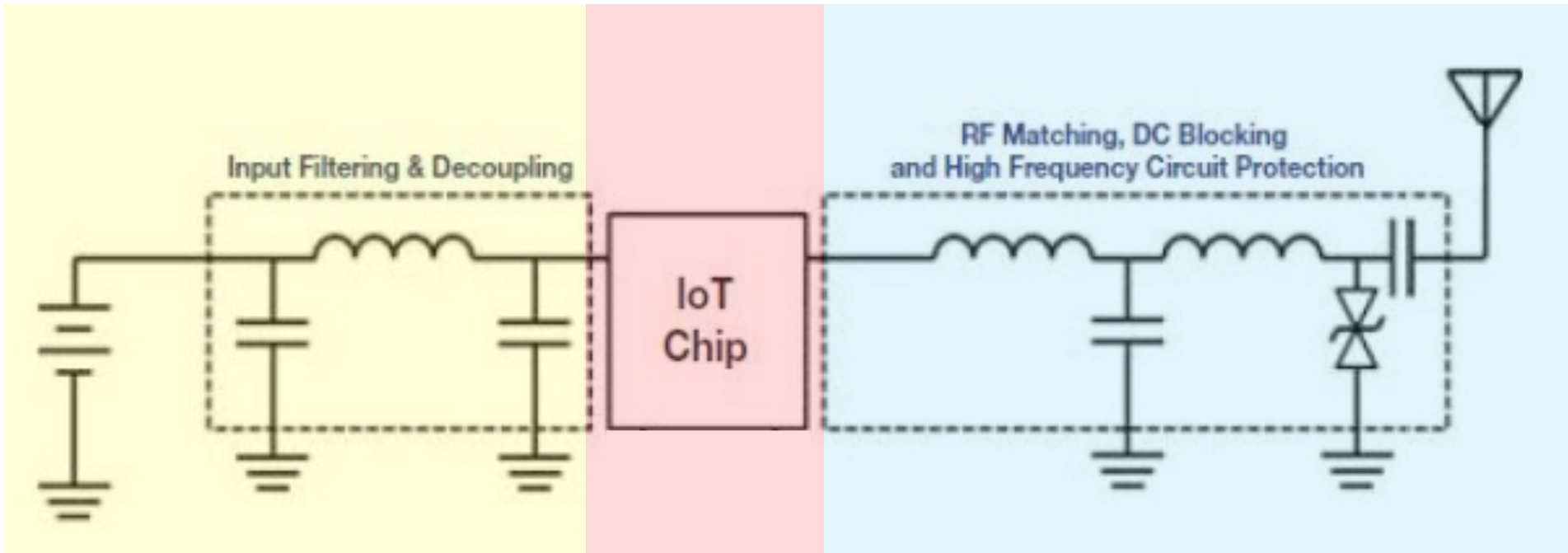


# SIMPLIFIED IoT STAMP PROFILE

Power

Processing

I/O

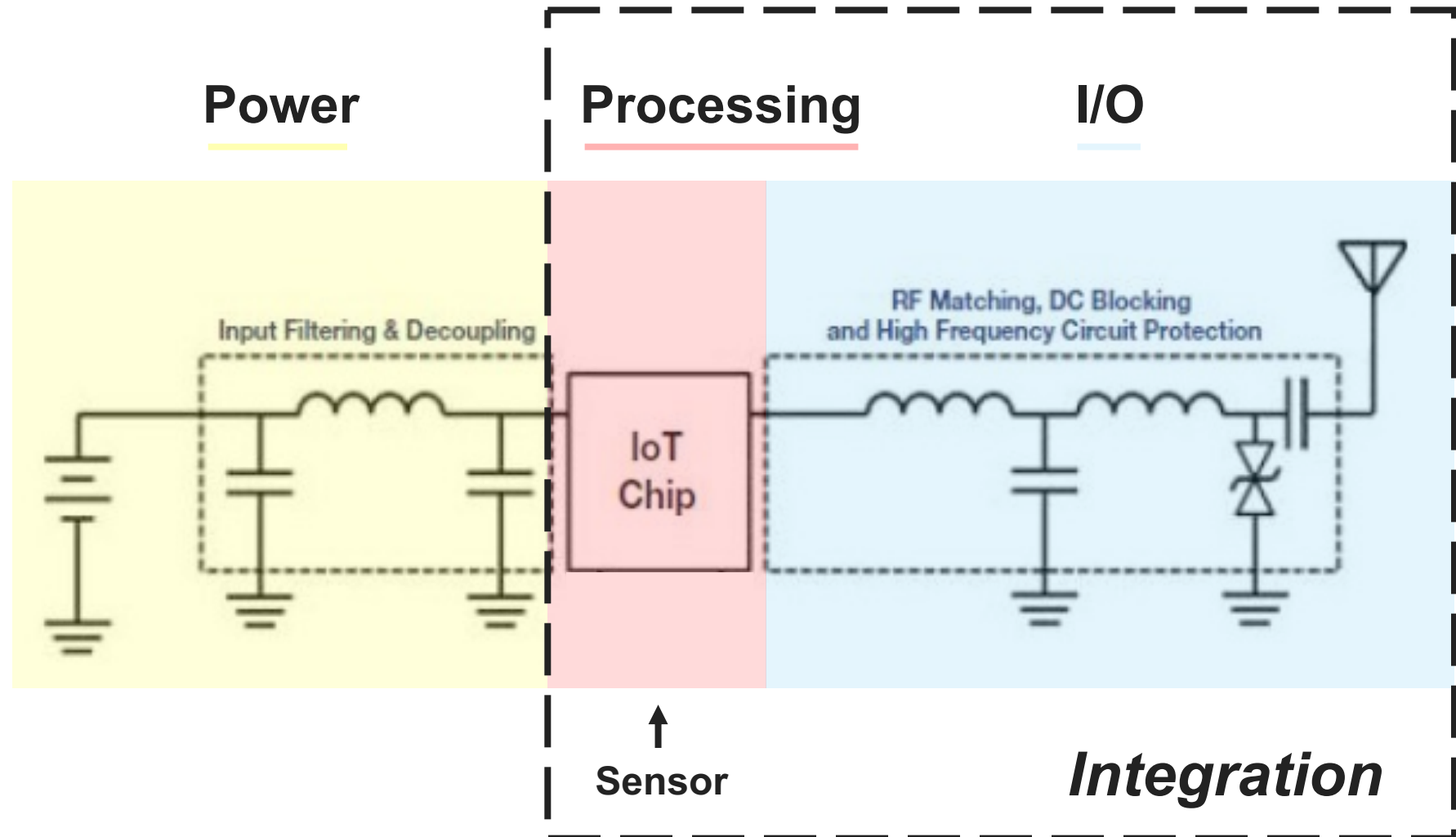


↑  
Sensor

# COST PRESSURES WILL DRIVE INTEGRATION

## Power: *Energy Harvesting*

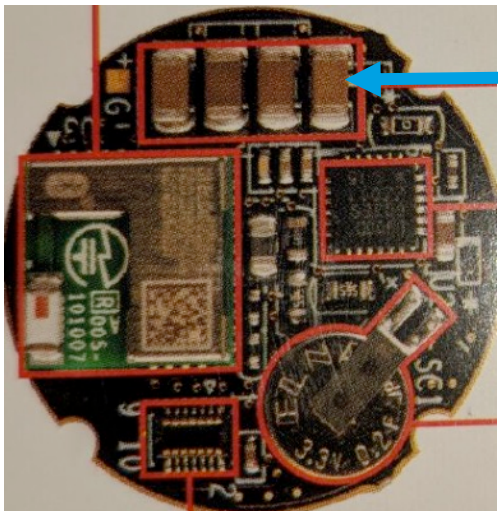
- Low Leakage, Hi Value Cap
- Hybrid Battery
- OR Battery Design



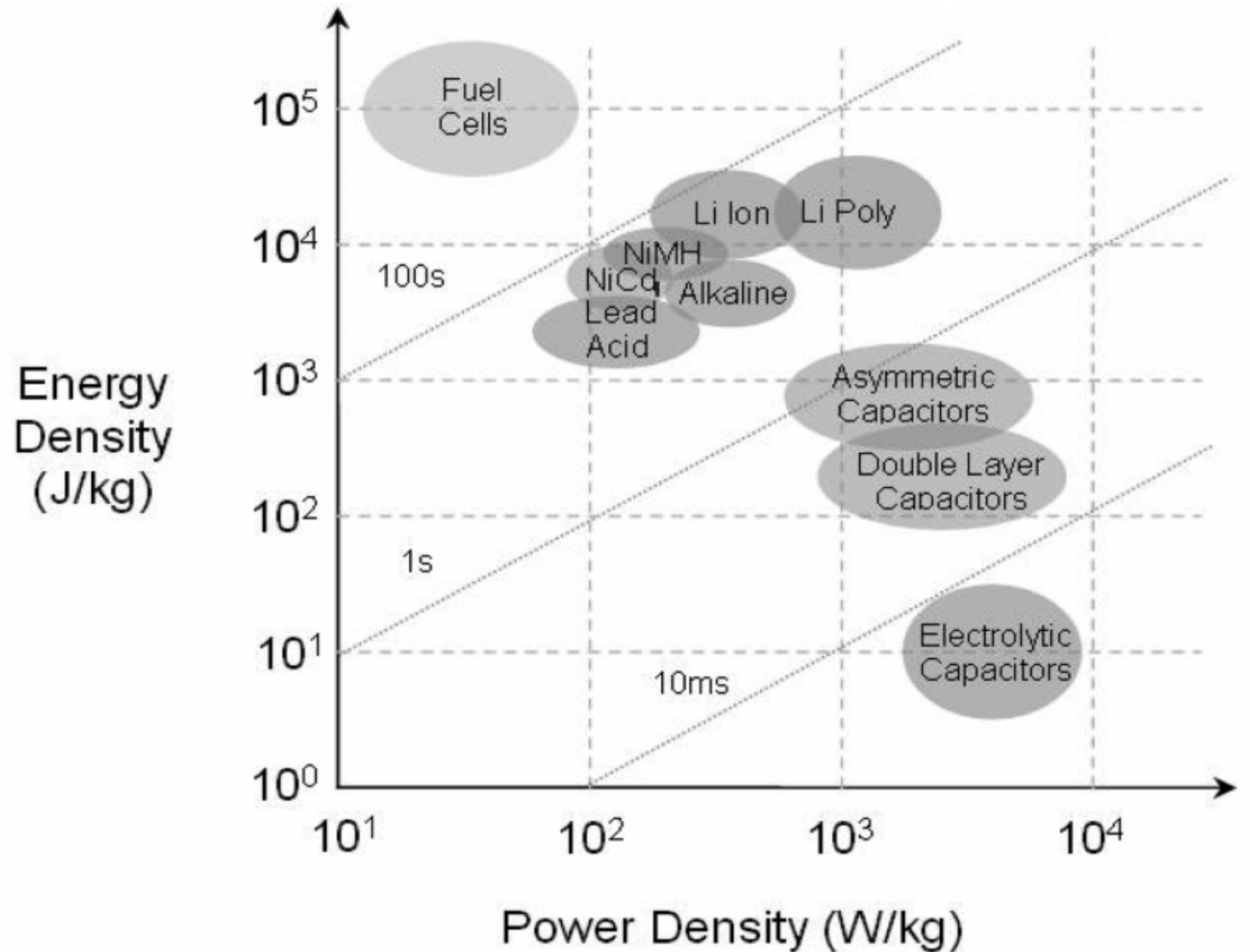
# WILL COST PRESSURES DRIVE INTEGRATION

## Power Of the Future:

- Small, Light, Cheap
- High Performance
- High Life Cycles
- Reliable
- Billions Made



What's Next?



# APPLICATION

## #3 CAPACITORS

### ELECTRIC VEHICLES

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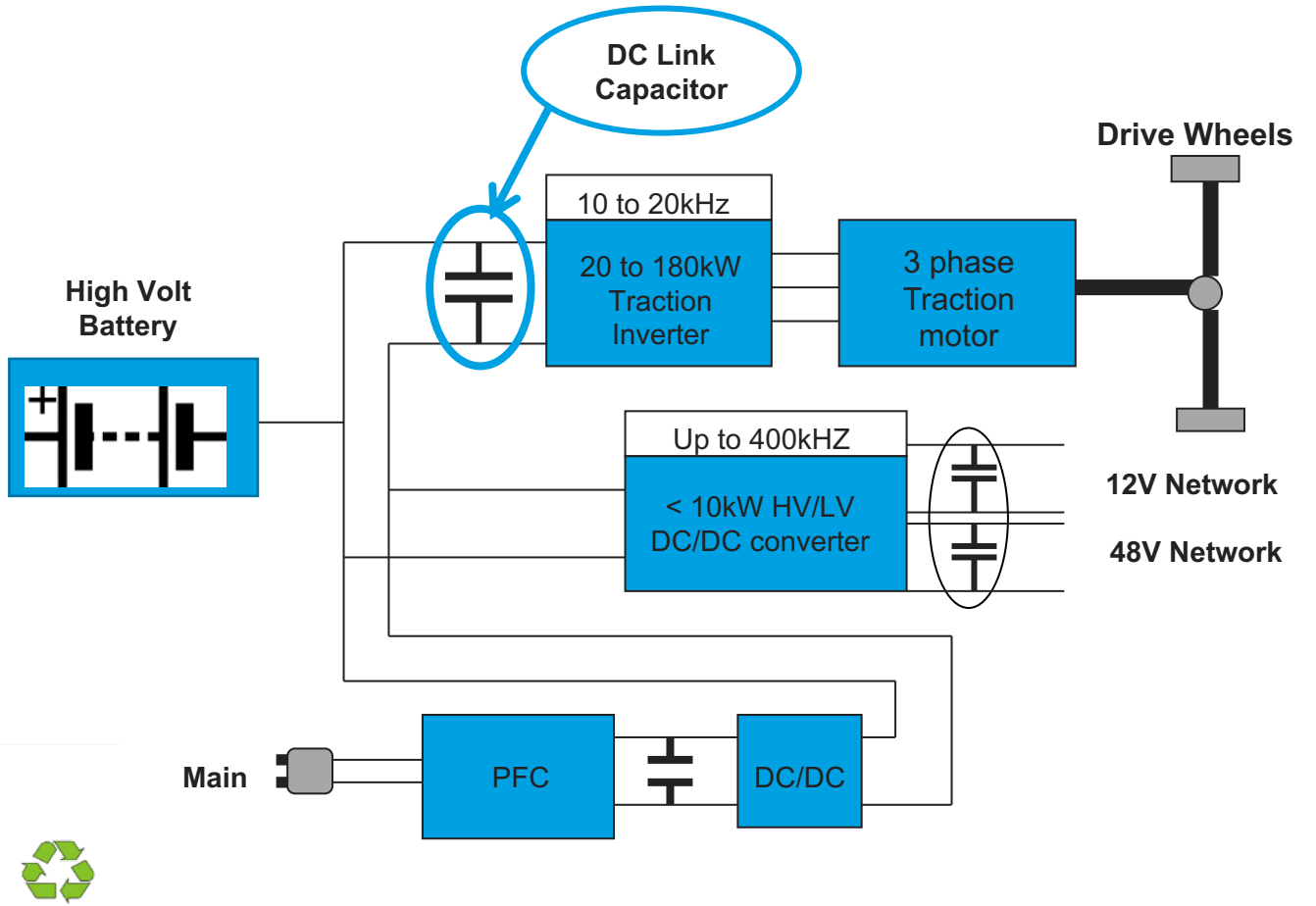
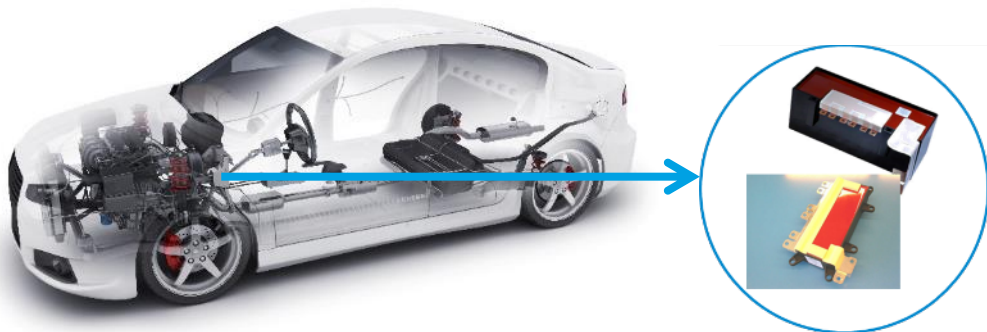
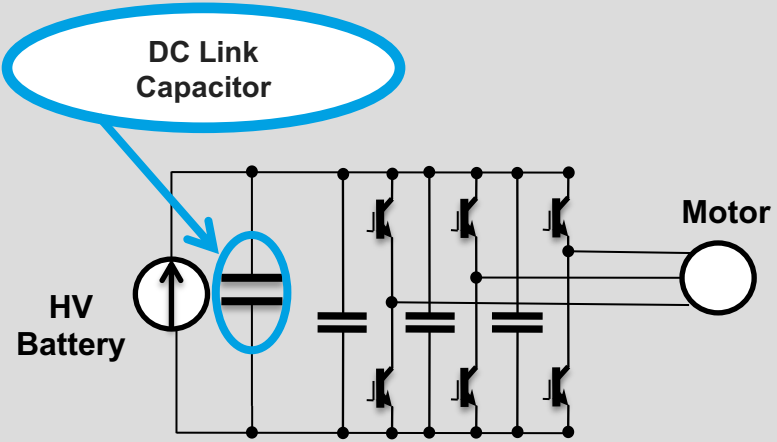


- EV Capacitor content massive - >10,000 capacitors
- Ranges from RF to Power Caps
- High Temp 150c/175c to decoupling & AC coupling on ADAS Drive – (critical for safety)
- Wireless charge circuitry

- Plug in charger & DC drive filtering
- DC Link Caps
- EMI Filter Caps
- Safety Caps

# HEV/EV TRACTION CHAIN

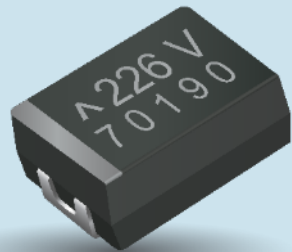
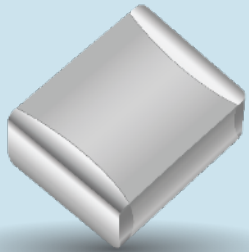
## TRACTION INVERTER



# EV POWER CAP OPTIONS & TRADE OFFS

## Application Needs:

More Cap, Higher Voltages,  
Smaller & Lighter Packages That  
Work At Hotter Temperatures

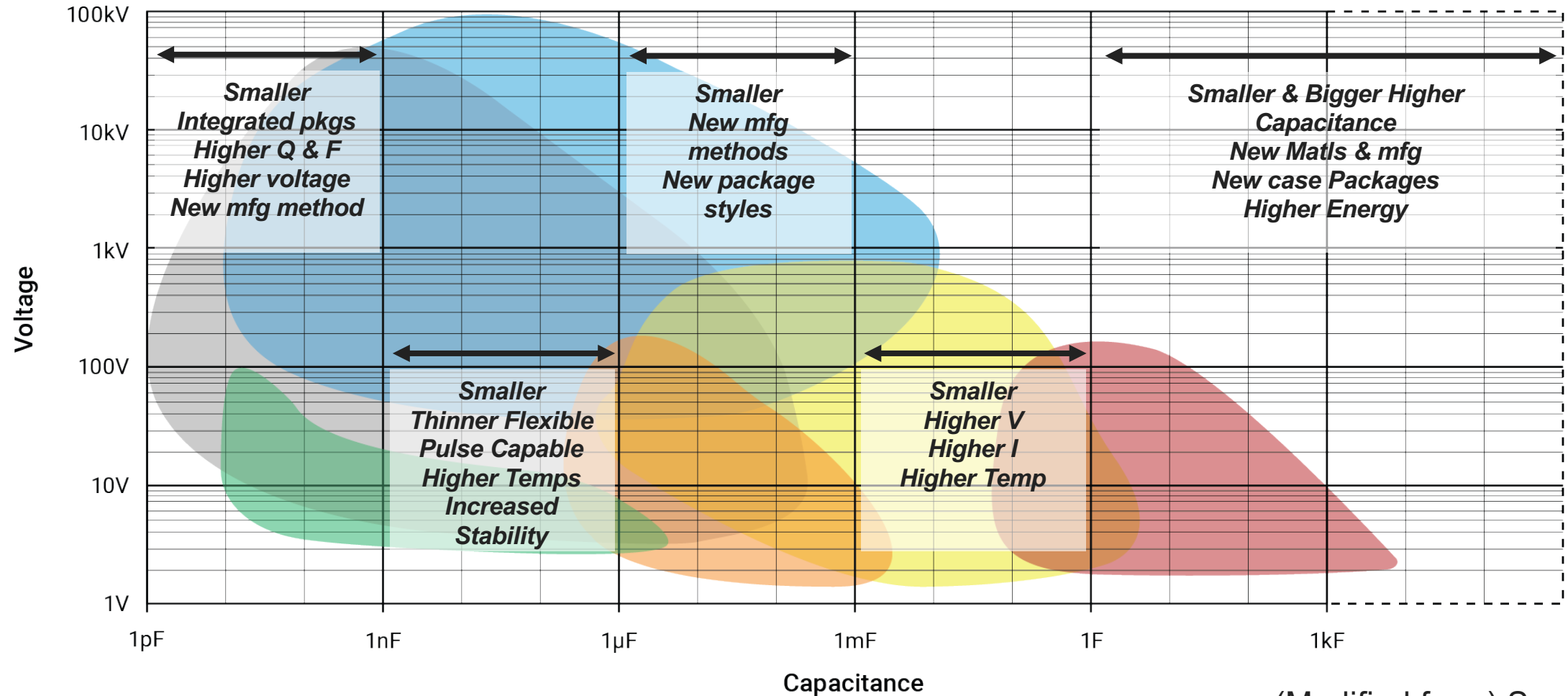


PARAMETER	FILM CAPACITOR	ELECROLYTIC CAPACITOR
Cost	High	Low
Size	Potentially smaller	Mixed volumetric efficiency
Surge Voltage Capability	2x rated voltage	1.2x rated voltage
Revere Voltage Capable	Yes	No
RMS Current	$\leq 1 \text{ A rms/ uF}$	$\leq 0.025 \text{ A rms/uF}$
MTBF	$\geq 10$ million hours	1 Million hours
Life Time	$\geq 100,000$ hours	$\geq 40,000$ hours
Storage	$> 10$ years	1 year
Environmentally friendly	Yes	No
End of life	Soft – failure loss of cap	Explosion Risk



WHERE ARE WE GOING & WHAT DOES THE FUTURE HOLD ?

# FUTURE TRENDS BY GROUP





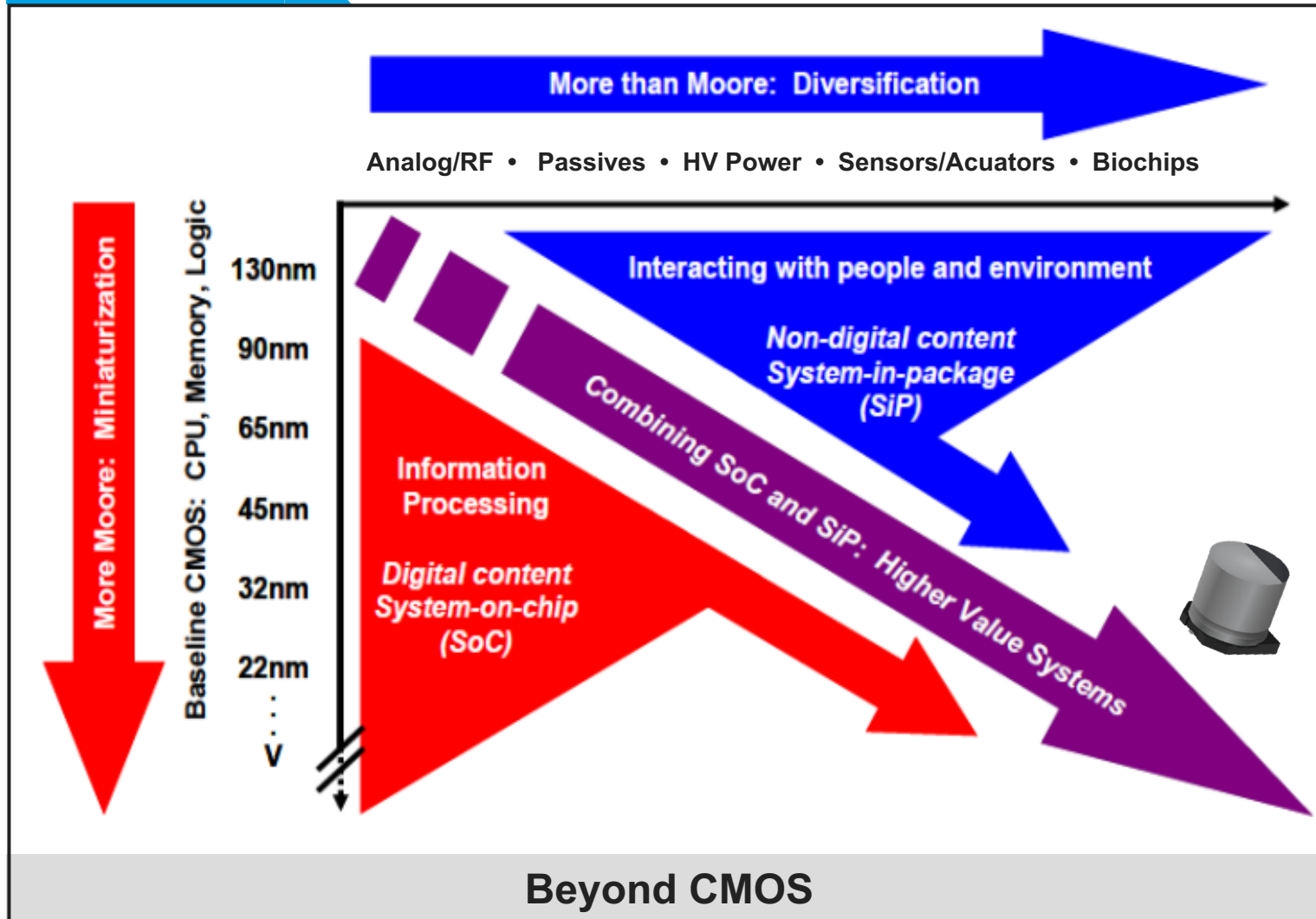
# WHERE ARE WE GOING & WHAT DOES THE FUTURE HOLD ?

PARAMETER	CAPACITOR TYPE			
	SMALL SIGNAL	RF	POWER	BULK GENERAL PURPOSE
Cap Value	↓↑	↓↑	↑	↑
Rated Voltage	↓↑	↑	↑	↓↑
Size	↓ →	↓ →	↓	↓
Temperature Stability	↓↑	↑	→	↑ →
DC Bias Stability Need	↑	↑	→	↑
Temperature Range	↑ →	↑ →	↑	↑
Frequency	↑	↑	↑	↑ →
Loss Characteristics	↓	↓	↓	↓

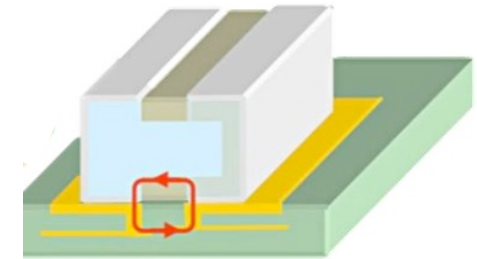
# AS ICs EVOLVE INTO SOCS & SIPS POWER QUALITY NEEDS INCREASE

Source:

ITRS

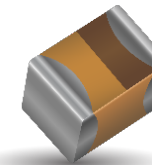


## Decoupling:

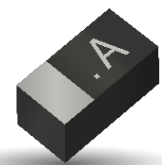


0508 LGA  
ESL ~ 27pH

## Bulk Filtering:

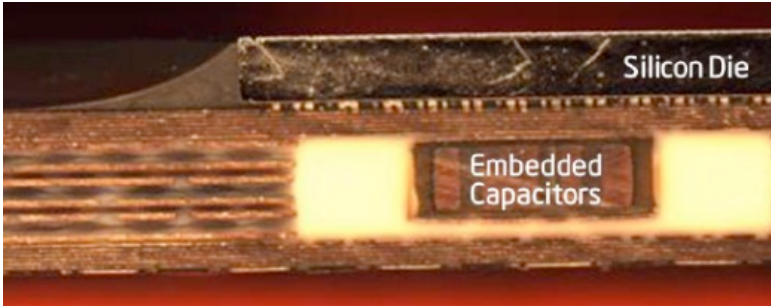


0402  
ESL ~ 1.1nH

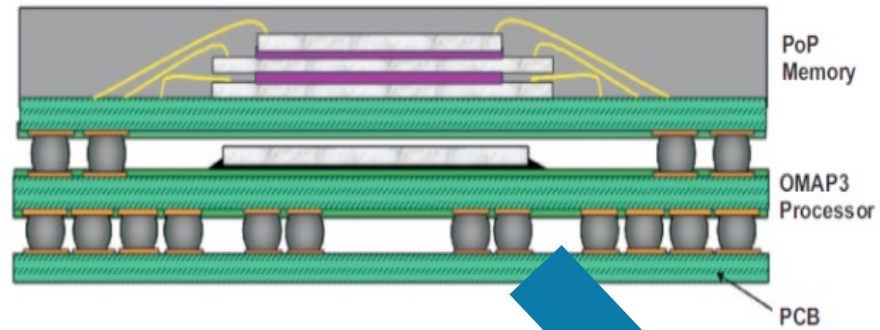


0402  
ESL ~ 1.1nH

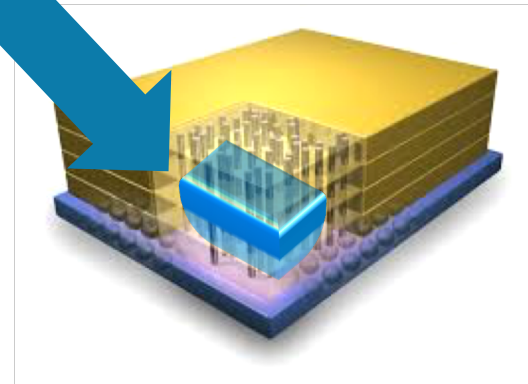
Source: Intel



Source: TI



Source: IBM NIST



Novel Designs

**ONE  
POSSIBLE  
EVOLUTION**

# WHAT IF THIS IS THE CAPACITOR ?



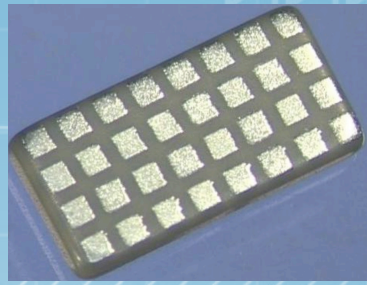
0.5F/cc

8.8J/cc

0.4F/g

3.7J/g

# Summary:



## THE FUTURE HAS UNIMAGINABLE UPSIDES

**Shortages Drive Design Innovation**

**Need for efficient caps is growing**

**Capacitor evolution driven by:**

- 1) IC Demands**
- 2) New Applications**
- 3) Emerging Active/Passive Packages**



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***THANK YOU.***



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